

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : YEH et al. Confirmation No: 8986
Appl. No. : 10/075,293
Filed : February 15, 2002
Title : METHOD OF REDUCING THICK FILM STRESS OF
SPIN-ON DIELECTRIC AND THE RESULTING SANDWICH
DIELECTRIC STRUCTURE

TC/A.U. : 2814
Examiner : H. Trinh

Docket No.: : YEHC3010/REF
Customer No: : 23364

I HEREBY CERTIFY THAT THIS
PAPER IS BEING FACSIMILE
TRANSMITTED TO THE U.S. P.T.O.
ON THE DATE SHOWN BELOW.

(PRINT) KATHLEEN DEPASSE
(SIGN) Kathleen Depasse
(DATE) Feb. 26, 2004

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is in further response to the Final Rejection of September 8, 2003. A timely filed Notice of Appeal with a one month extension of time was filed on January 8, 2004 as full response to the Final Rejection. The appeal brief is now due on March 8, 2004. The present amendment is being filed in an effort to place the application in condition for allowance and to avoid the necessity to proceed with the preparation and filing of an appeal brief.

Please amend the above-identified application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.